



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Farnworth et al.

Serial No.: 09/928,478

Filed: August 13, 2001

For: SEMICONDUCTOR DEVICE
INCLUDING COMBED BOND PAD
OPENING, ASSEMBLIES AND METHODS

Confirmation No.: 7943

Examiner: J. Vigushin

Group Art Unit: 2827

Attorney Docket No.: 2269-3401.5US
(97-0710.05/US)

Notice of Allowance Mailed:

September 18, 2003

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

December 15, 2003
Date

Signature

Deidra J. Pfeil

Name (Type/Print)

AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

Amendments to the Title appear on page 3 of this paper.

Amendments to the Specification begin on page 4 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 6 of this paper.

Remarks begin on page 9 of this paper.

Serial No. 09/928,478

IN THE TITLE:

The title has been amended herein. Pursuant to 37 C.F.R. §§ 1.121 and 1.125 (as amended to date), please enter the title as amended.

**SEMICONDUCTOR DEVICE INCLUDING COMBED BOND PAD
OPENING,~~ASSEMBLIES AND METHODS~~**